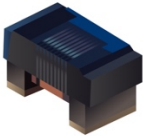


MATERIAL DECLARATION SHEET

Material Number	CWF2414 Series			
Product Line	Chip Inductor			
Compliance Date	2020/06/29			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)	
1	Ferrite body	Ferrite Ni-Zn Series	0.01064	Iron oxide	1309-37-1	62.000	47.120	76.00	
				Nickel oxide	1313-99-1	11.000	8.360		
				Zinc oxide	1314-13-2	20.000	15.200		
				Copper oxide	1317-38-0	7.000	5.320		
2	Copper/ Coating	Copper Wire	0.00168	Copper	7440-50-8	100.000	12.000	15.00	
		Copper Colored Coating On The Magnet Wire_SFHW	0.00042	Polyurethane Resin	26680-22-8	100.000	3.000		
3	Terminal	Silver paste_DP4303W	0.00042	Silver	7440-22-4	73.68	2.2104	3.00	
				Silicon dioxide	60676-86-0	15.79	0.4737		
				Resins	9004-57-3	10.53	0.3159		
4	Solder Base	S Nickel Pellets	0.00014	Nickel	7440-02-0	100.000	1.000	1.00	
5	Solder	Lead Free Solder	0.00014	Tin	7440-31-5	100.000	1.000	1.00	
6	Back Membrane	UV Adhesive	0.00056	Diacrylate compound	42978-66-5	100.000	4.00	4.00	
			Total weight						0.014

This Document was updated on: 2020/06/29

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.